Renesas Electronics America Inc - M306N4FGTFP#UKJ Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	M16C/60
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I²C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	85
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m306n4fgtfp-ukj

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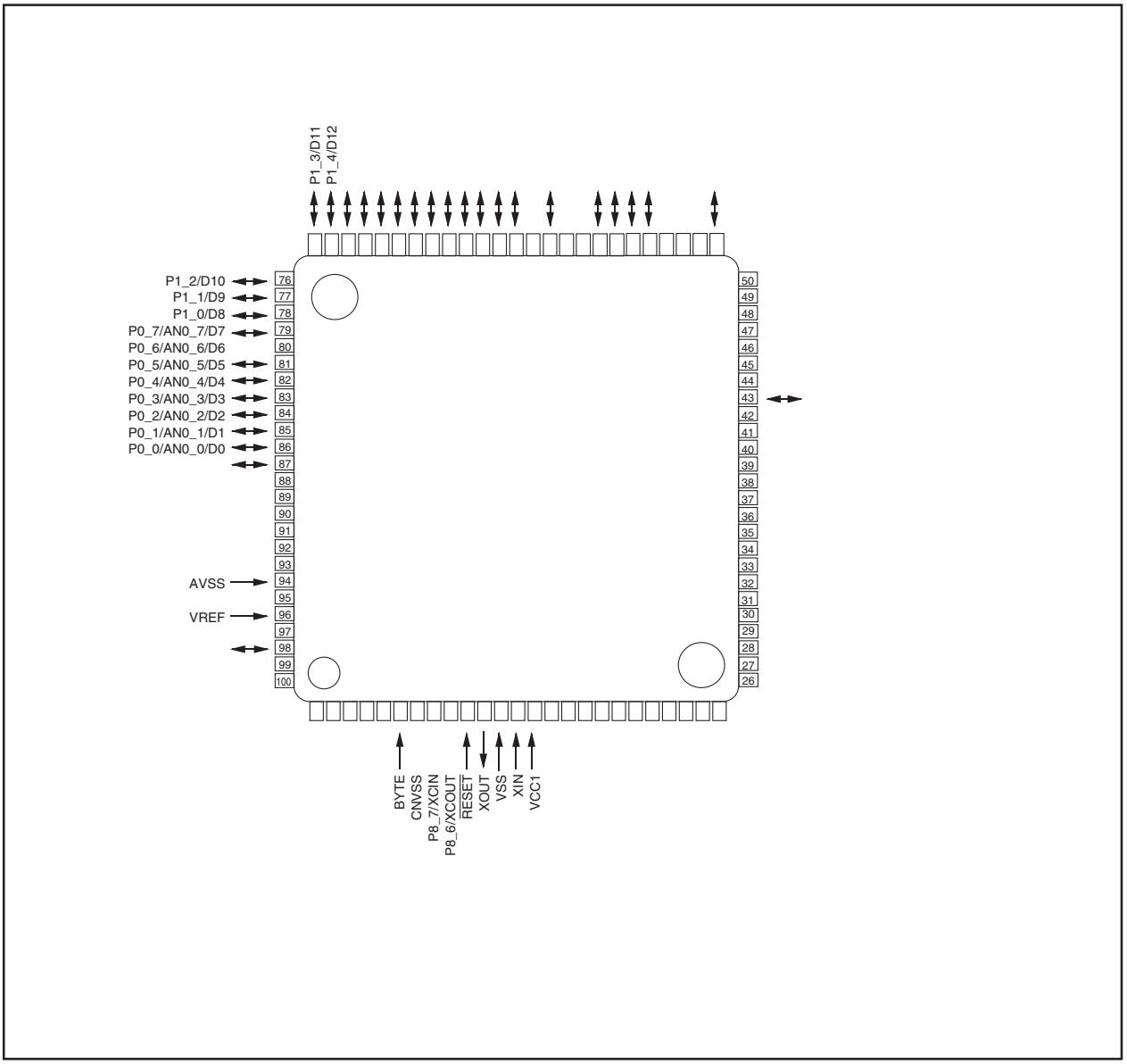


Figure 1.4 Pin Assignments (Top View) (2)

Table 1.4 List of Pin Names (2)

Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	CAN Module Pin	Bus Control Pin
FP	GP								
51	49		P4_3						A19
52	50		P4_2						A18
53	51		P4_1						A17
54	52		P4_0						A16
55	53		P3_7						A15
56	54		P3_6						A14
57	55		P3_5						A13
58	56		P3_4						A12
59	57		P3_3						A11
60	58		P3_2						A10
61	59		P3_1						A9
62	60	VCC2							
63	61		P3_0						A8(/-/D7)
64	62	VSS							
65	63		P2_7				AN2_7		A7(/D7/D6)
66	64		P2_6				AN2_6		A6(/D6/D5)
67	65		P2_5				AN2_5		A5(/D5/D4)
68	66		P2_4				AN2_4		A4(/D4/D3)
69	67		P2_3				AN2_3		A3(/D3/D2)
70	68		P2_2				AN2_2		A2(/D2/D1)
71	69		P2_1				AN2_1		A1(/D1/D0)
72	70		P2_0				AN2_0		A0(/D0/-)
73	71		P1_7	$\overline{\text{INT5}}$					D15
74	72		P1_6	$\overline{\text{INT4}}$					D14
75	73		P1_5	$\overline{\text{INT3}}$					D13
76	74		P1_4						D12
77	75		P1_3						D11
78	76		P1_2						D10
79	77		P1_1						D9
80	78		P1_0						D8
81	79		P0_7				AN0_7		D7
82	80		P0_6				AN0_6		D6
83	81		P0_5				AN0_5		D5
84	82		P0_4				AN0_4		D4
85	83		P0_3				AN0_3		D3
86	84		P0_2				AN0_2		D2
87	85		P0_1				AN0_1		D1
88	86		P0_0				AN0_0		D0
89	87		P10_7	$\overline{\text{KI3}}$			AN7		
90	88		P10_6	$\overline{\text{KI2}}$			AN6		
91	89		P10_5	$\overline{\text{KI1}}$			AN5		
92	90		P10_4	$\overline{\text{KI0}}$			AN4		
93	91		P10_3				AN3		
94	92		P10_2				AN2		
95	93		P10_1				AN1		
96	94	AVSS							
97	95		P10_0				AN0		
98	96	VREF							
99	97	AVCC							
100	98		P9_7				$\overline{\text{ADTRG}}$		

FP: PRQP0100JB-A (100P6S-A), GP: PLQP0100KB-A (100P6Q-A)

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU has 13 registers. Of these, R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two register banks.

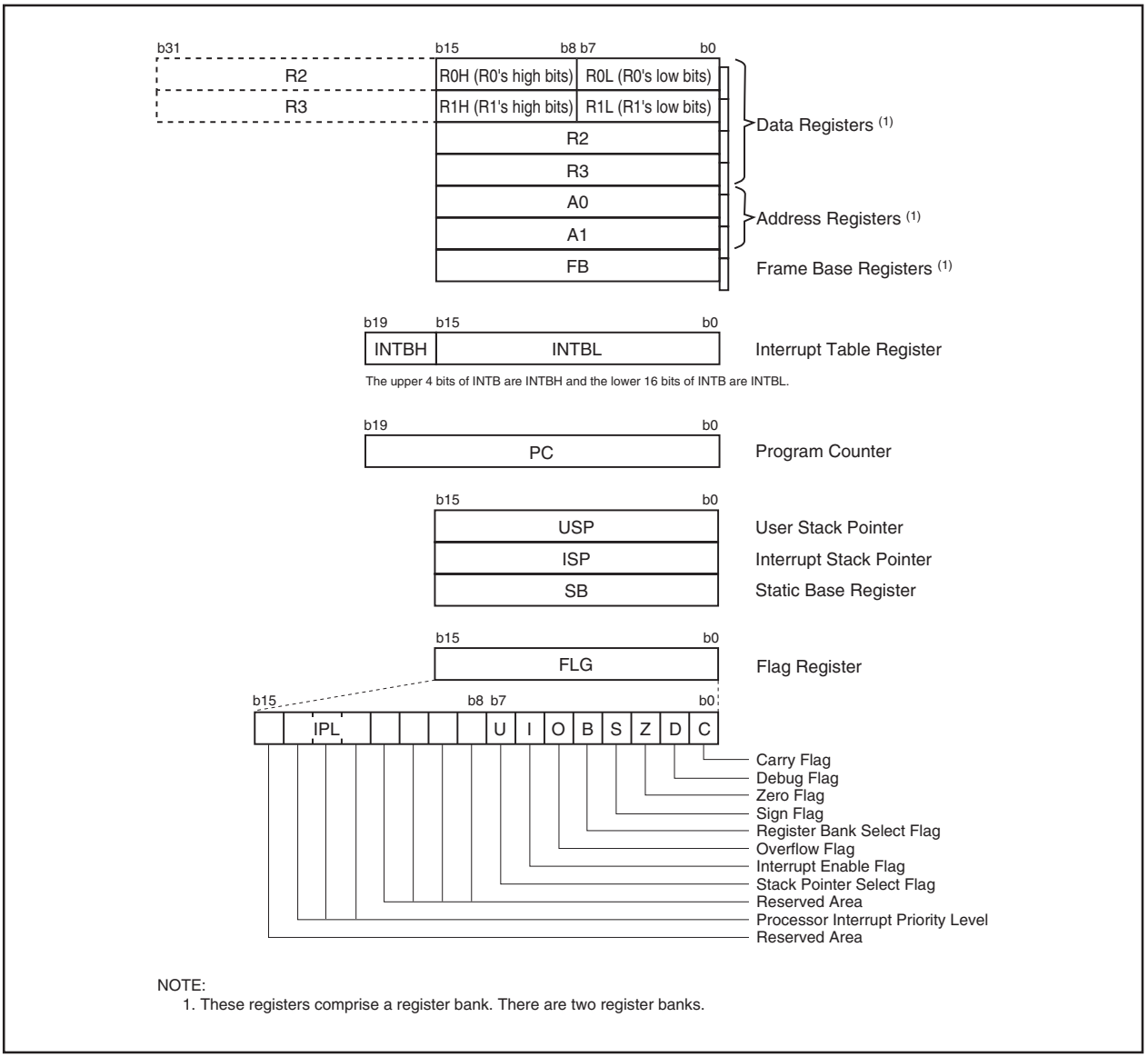


Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers. R1H and R1L are the same as R0H and R0L. Conversely R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

The A0 register consists of 16 bits, and is used for address register indirect addressing and address register relative addressing. They also are used for transfers and arithmetic/logic operations. A1 is the same as A0.

In some instructions, A1 and A0 can be combined for use as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is configured with 16 bits, and is used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is configured with 20 bits, indicating the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is configured with 20 bits, indicating the address of an instruction to be executed.

2.6 User Stack Pointer (USP), Interrupt Stack Pointer (ISP)

Stack pointer (SP) comes in two types: USP and ISP, each configured with 16 bits.
Your desired type of stack pointer (USP or ISP) can be selected by the U flag of FLG.

2.7 Static Base Register (SB)

SB is configured with 16 bits, and is used for SB relative addressing.

2.8 Flag Register (FLG)

FLG consists of 11 bits, indicating the CPU status.

2.8.1 Carry Flag (C Flag)

This flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic/logic unit.

2.8.2 Debug Flag (D Flag)

This flag is used exclusively for debugging purpose. During normal use, set to 0.

2.8.3 Zero Flag (Z Flag)

This flag is set to 1 when an arithmetic operation resulted in 0; otherwise, it is 0.

2.8.4 Sign Flag (S Flag)

This flag is set to 1 when an arithmetic operation resulted in a negative value; otherwise, it is 0.

2.8.5 Register Bank Select Flag (B Flag)

Register bank 0 is selected when this flag is 0; register bank 1 is selected when this flag is 1.

2.8.6 Overflow Flag (O Flag)

This flag is set to 1 when the operation resulted in an overflow; otherwise, it is 0.

2.8.7 Interrupt Enable Flag (I Flag)

This flag enables a maskable interrupt.
Maskable interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when the interrupt request is accepted.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is 0; USP is selected when the U flag is 1.
The U flag is set to 0 when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has priority greater than IPL, the interrupt request is enabled.

2.8.10 Reserved Area

When white to this bit, write 0. When read, its content is undefined.

3. Memory

Figure 3.1 shows a Memory Map. The address space extends the 1 Mbyte from address 00000h to FFFFFh. The internal ROM is allocated in a lower address direction beginning with address FFFFFh. For example, a 128-Kbyte internal ROM is allocated to the addresses from E0000h to FFFFFh.

As for the flash memory version, 4-Kbyte space (block A) exists in 0F000h to 0FFFFh. 4-Kbyte space is mainly for storing data. In addition to storing data, 4-Kbyte space also can store programs.

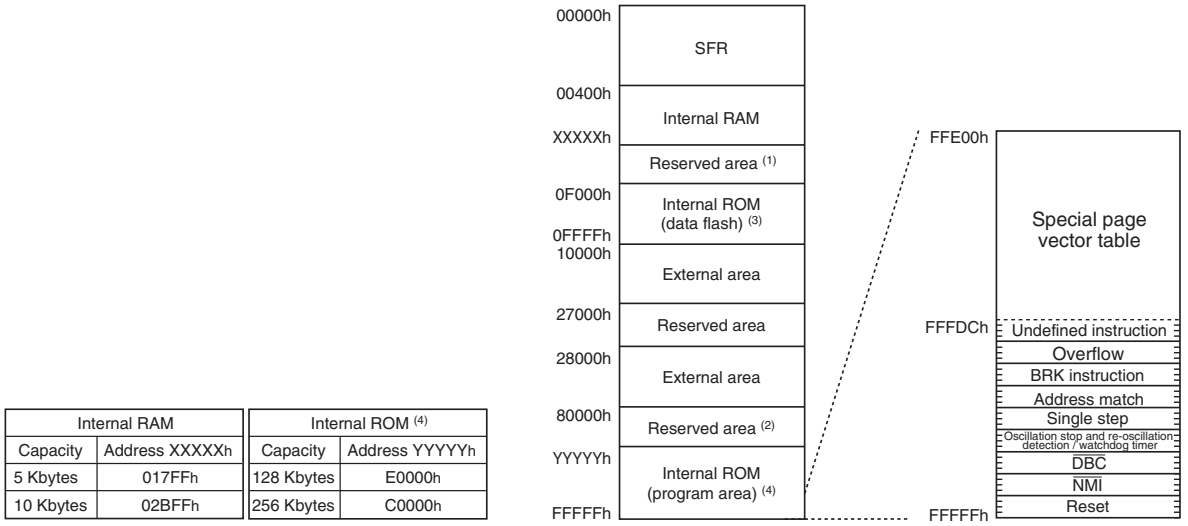
The fixed interrupt vector table is allocated to the addresses from FFFDCh to FFFFFh. Therefore, store the start address of each interrupt routine here.

The internal RAM is allocated in an upper address direction beginning with address 00400h. For example, a 5-Kbyte internal RAM is allocated to the addresses from 00400h to 017FFh. In addition to storing data, the internal RAM also stores the stack used when calling subroutines and when interrupts are generated.

The Special Function Registers (SFRs) are allocated to the addresses from 00000h to 003FFh. Peripheral function control registers are located here. Of the SFR, any area which has no functions allocated is reserved for future use and cannot be accessed by user.

The special page vector table is allocated to the addresses from FFE00h to FFFDBh. This vector is used by the JMPS or JSRS instruction. For details, refer to **M16C/60, M16C/20, M16C/Tiny Series Software Manual**.

In memory expansion and microprocessor modes, some areas are reserved for future use and cannot be used by users.



Internal RAM		Internal ROM (4)	
Capacity	Address XXXXXh	Capacity	Address YYYYYh
5 Kbytes	017FFh	128 Kbytes	E0000h
10 Kbytes	02BFFh	256 Kbytes	C0000h

NOTES:
1. During memory expansion mode or microprocessor mode, cannot be used.
2. In memory expansion mode, cannot be used.
3. As for the flash memory version, 4-Kbyte space (block A) exists.
4. When using the masked ROM version, write nothing to internal ROM area.
5. Shown here is a memory map for the case where the PM10 bit in the PM1 register is 1 (block A enabled, addresses 10000h to 26FFFh for $\overline{CS2}$ area) and the PM13 bit in the PM1 register is 1 (internal RAM area is expanded over 192 Kbytes).

Figure 3.1 Memory Map

4. Special Function Registers (SFRs)

An SFR (Special Function Register) is a control register for a peripheral function.
Tables 4.1 to 4.16 list the SFR Information.

Table 4.1 SFR Information (1) [3]

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0 [1]	PM0	00000000b (CNVSS pin is "L") 00000011b (CNVSS pin is "H")
0005h	Processor Mode Register 1	PM1	00001000b
0006h	System Clock Control Register 0	CM0	01001000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Chip Select Control Register	CSR	00000001b
0009h	Address Match Interrupt Enable Register	AIER	XXXXXX00b
000Ah	Protect Register	PRCR	XX000000b
000Bh			
000Ch	Oscillation Stop Detection Register [2]	CM2	0X000000b
000Dh			
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00XXXXXXb
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			X0h
0013h			
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			X0h
0017h			
0018h			
0019h			
001Ah			
001Bh	Chip Select Expansion Control Register	CSE	00h
001Ch	PLL Control Register 0	PLC0	0001X010b
001Dh			
001Eh	Processor Mode Register 2	PM2	XXX00000b
001Fh			
0020h	DMA0 Source Pointer	SAR0	XXh
0021h			XXh
0022h			XXh
0023h			
0024h	DMA0 Destination Pointer	DAR0	XXh
0025h			XXh
0026h			XXh
0027h			
0028h	DMA0 Transfer Counter	TCR0	XXh
0029h			XXh
002Ah			
002Bh			
002Ch	DMA0 Control Register	DM0CON	00000X00b
002Dh			
002Eh			
002Fh			
0030h	DMA1 Source Pointer	SAR1	XXh
0031h			XXh
0032h			XXh
0033h			
0034h	DMA1 Destination Pointer	DAR1	XXh
0035h			XXh
0036h			XXh
0037h			
0038h	DMA1 Transfer Counter	TCR1	XXh
0039h			XXh
003Ah			
003Bh			
003Ch	DMA1 Control Register	DM1CON	00000X00b
003Dh			
003Eh			
003Fh			

X: Undefined

NOTES:
1. Bits PM00 and PM01 in the PM0 register do not change at software reset, watchdog timer reset and oscillation stop detection reset.
2. Bits CM20, CM21, and CM27 in the CM2 register do not change at oscillation stop detection reset.
3. Blank spaces are reserved. No access is allowed.

Table 4.14 SFR Information (14) (1)

Address	Register	Symbol	After Reset
0340h	CAN1 Message Box 14: Identifier / DLC		XXh
0341h			XXh
0342h			XXh
0343h			XXh
0344h			XXh
0345h			XXh
0346h	CAN1 Message Box 14: Data Field		XXh
0347h			XXh
0348h			XXh
0349h			XXh
034Ah			XXh
034Bh			XXh
034Ch			XXh
034Dh			XXh
034Eh	CAN1 Message Box 14: Time Stamp		XXh
034Fh			XXh
0350h	CAN1 Message Box 15: Identifier / DLC		XXh
0351h			XXh
0352h			XXh
0353h			XXh
0354h			XXh
0355h			XXh
0356h	CAN1 Message Box 15: Data Field		XXh
0357h			XXh
0358h			XXh
0359h			XXh
035Ah			XXh
035Bh			XXh
035Ch			XXh
035Dh			XXh
035Eh	CAN1 Message Box 15: Time Stamp		XXh
035Fh			XXh
0360h	CAN1 Global Mask Register	C1GMR	XXh
0361h			XXh
0362h			XXh
0363h			XXh
0364h			XXh
0365h			XXh
0366h	CAN1 Local Mask A Register	C1LMAR	XXh
0367h			XXh
0368h			XXh
0369h			XXh
036Ah			XXh
036Bh			XXh
036Ch	CAN1 Local Mask B Register	C1LMBR	XXh
036Dh			XXh
036Eh			XXh
036Fh			XXh
0370h			XXh
0371h			XXh
0372h			
0373h			
0374h			
0375h			
0376h			
0377h			
0378h			
0379h			
037Ah			
037Bh			
037Ch			
037Dh			
037Eh			
037Fh			

X: Undefined

NOTE:
1. Blank spaces are reserved. No access is allowed.

Switching Characteristics VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.23 Memory Expansion Mode and Microprocessor Mode (for setting with no wait)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.2		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		–4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$ f(BCLK) is 12.5 MHz or less.

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
   Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
   Hold time of data bus is expressed in
   $t = -CR \times \ln (1 - V_{OL} / V_{CC})$
   by a circuit of the right figure.
   For example, when $V_{OL} = 0.2\ V_{CC}$, C = 30 pF, R =1 kΩ, hold time of output "L" level is
   $t = -30\text{ pF} \times 1\text{ k}\Omega \times \ln (1 - 0.2\ V_{CC} / V_{CC}) = 6.7$ ns.

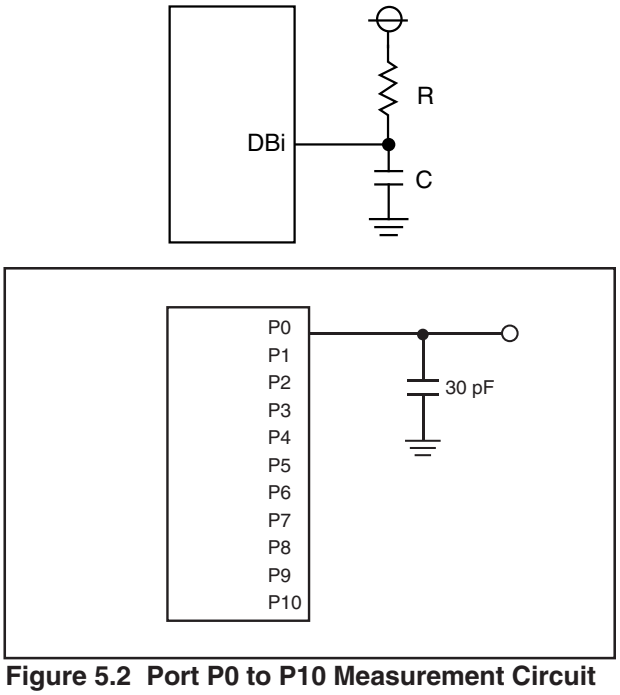
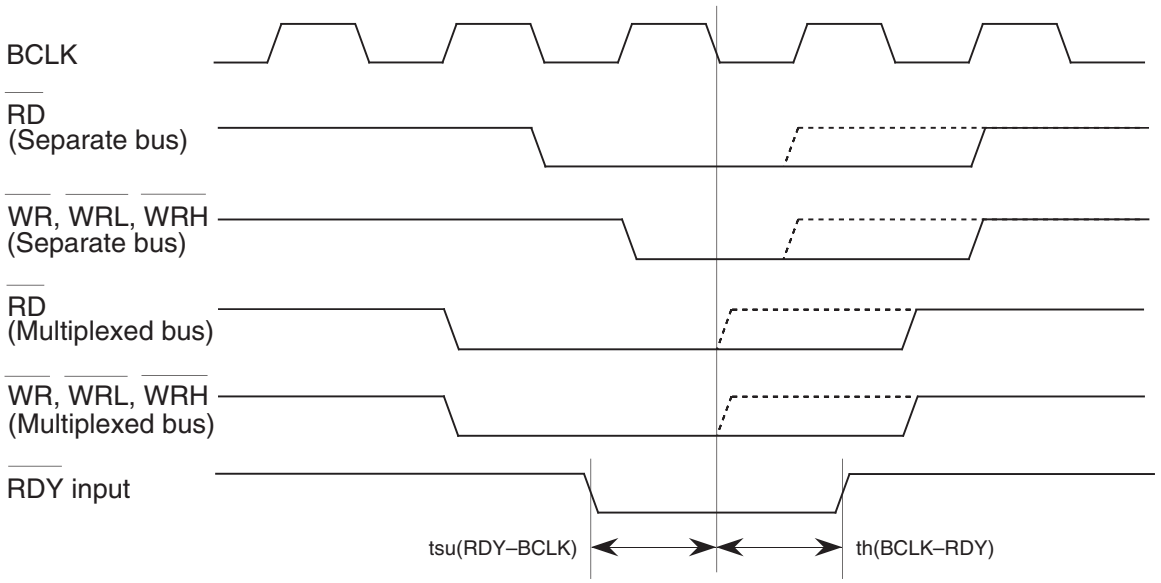


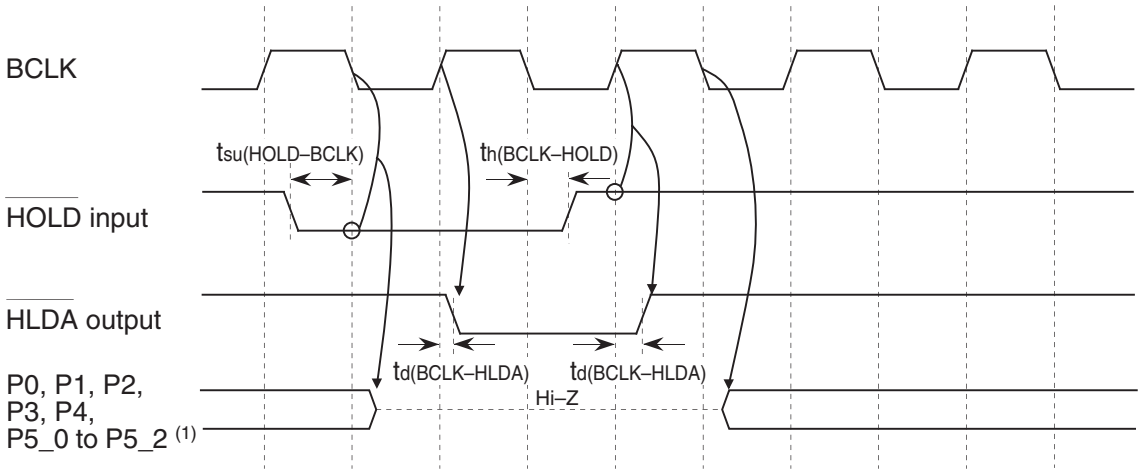
Figure 5.2 Port P0 to P10 Measurement Circuit

Memory Expansion Mode and Microprocessor Mode **VCC = 5 V**

(Effective for setting with wait)



(Common to setting with wait and setting without wait)



NOTE:
1. The above pins are set to high-impedance regardless of the input level of the BYTE pin, the PM06 bit in the PM0 register, and the PM11 bit in the PM1 register.

Measuring conditions :
- VCC = 5 V
- Input timing voltage : Determined with V_{IL} = 1.0 V, V_{IH} = 4.0 V
- Output timing voltage: Determined with V_{OL} = 2.5 V, V_{OH} = 2.5 V

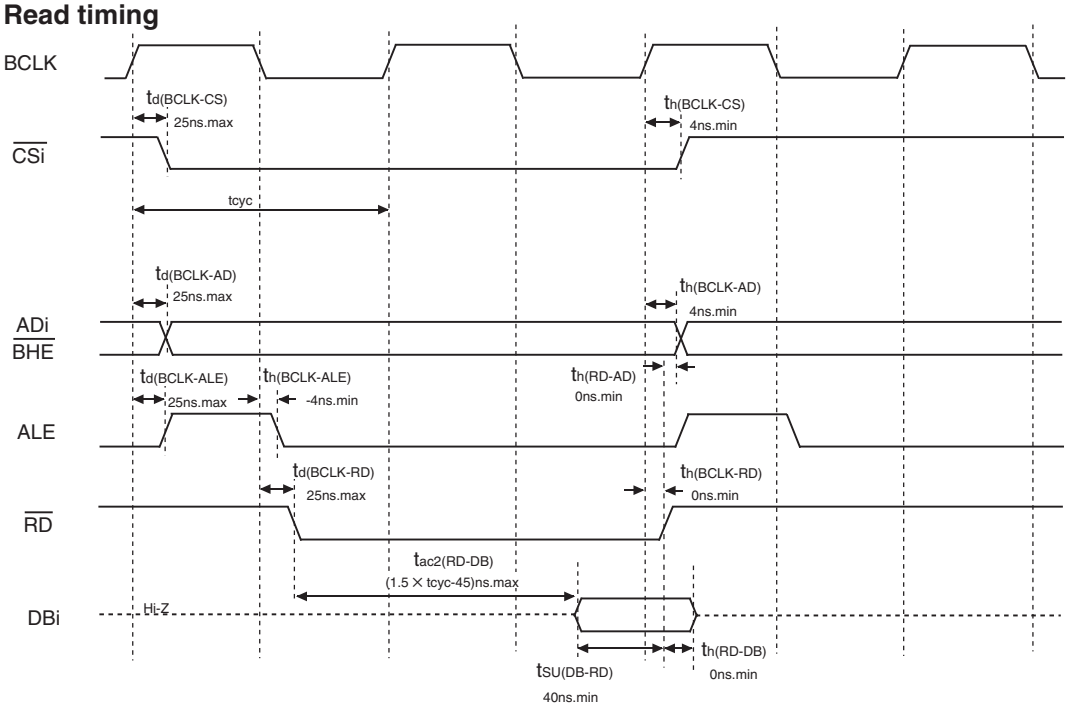
Figure 5.4 Timing Diagram (2)

Memory Expansion Mode and Microprocessor Mode

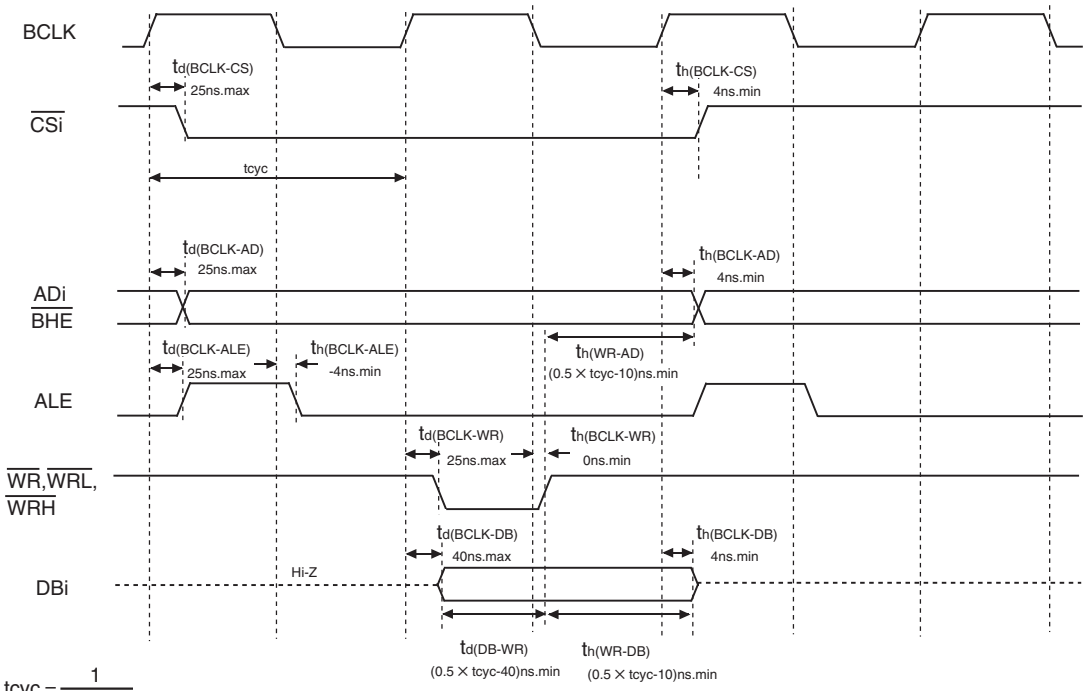
VCC = 5 V

(For 1-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage : V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Output timing voltage : V_{OL} = 0.4 V, V_{OH} = 2.4 V

Figure 5.6 Timing Diagram (4)

Table 5.31 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Measuring Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during powering-on	VCC = 3.0 to 5.5 V			2	ms
$t_{d(R-S)}$	STOP release time				150	µs
$t_{d(W-S)}$	Low power dissipation mode wait mode release time				150	µs

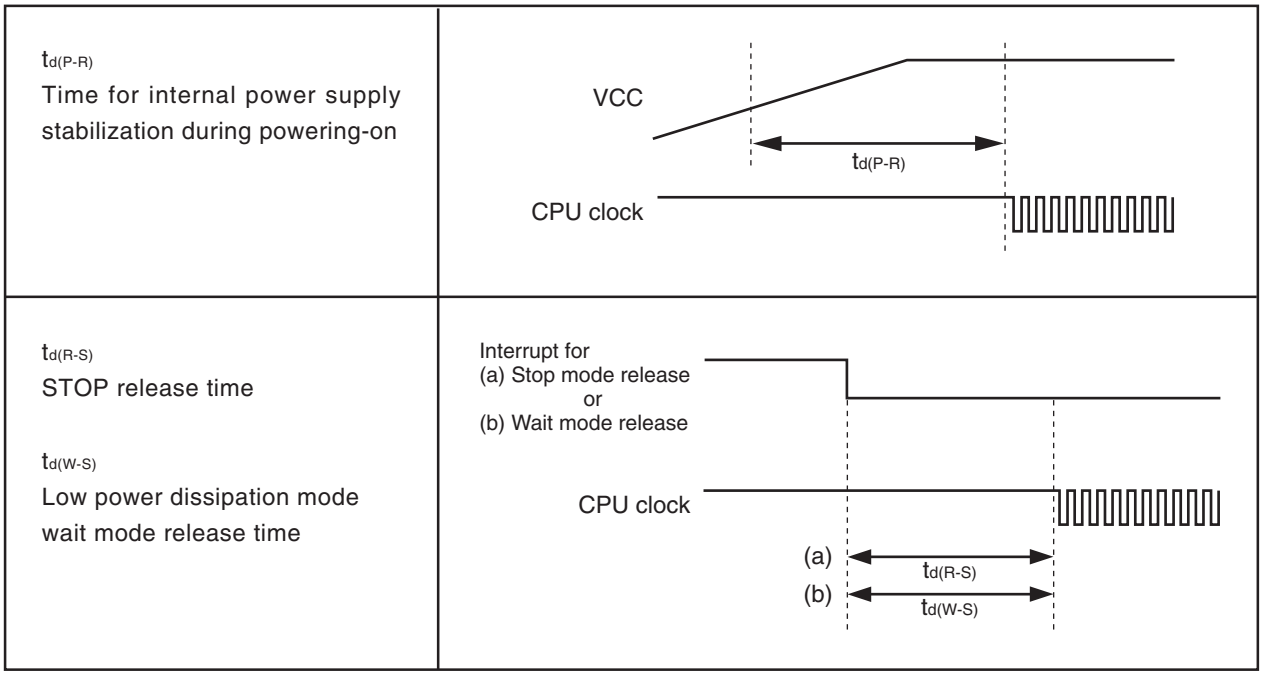


Figure 5.11 Power Supply Circuit Timing Diagram

Table 5.33 Electrical Characteristics (2) [1]

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power supply current (VCC = 3.0 to 5.5 V)	In single-chip mode, the output pins are open and other pins are VSS.	Mask ROM	f(BCLK) = 24 MHz, PLL operation, No division		20	36	mA
				On-chip oscillation, No division		1		mA
			Flash memory	f(BCLK) = 24 MHz, PLL operation, No division		22	38	mA
				On-chip oscillation, No division		1.8		mA
			Flash memory program	f(BCLK) = 10 MHz, VCC = 5 V		15		mA
			Flash memory erase	f(BCLK) = 10 MHz, VCC = 5 V		25		mA
			Mask ROM	f(BCLK) = 32 kHz, Low power dissipation mode, ROM [2]		25		µA
			Flash memory	f(BCLK) = 32 kHz, Low power dissipation mode, RAM [2]		25		µA
				f(BCLK) = 32 kHz, Low power dissipation mode, Flash memory [2]		420		µA
			Mask ROM Flash memory	On-chip oscillation, Wait mode		50		µA
				f(BCLK) = 32 kHz, Wait mode [3], Oscillation capacity High		8.5		µA
				f(BCLK) = 32 kHz, Wait mode [3], Oscillation capacity Low		3.0		µA
				Stop mode, Topr = 25°C		0.8	3.0	µA

NOTES:
1. Referenced to VCC = 3.0 to 5.5 V, VSS = 0 V at Topr = –40 to 85°C, f(BCLK) = 24 MHz unless otherwise specified.
2. This indicates the memory in which the program to be executed exists.
3. With one timer operated using fC32.

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.36 Timer A Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	100		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	40		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	40		ns

Table 5.37 Timer A Input (Gating Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	400		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	200		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	200		ns

Table 5.38 Timer A Input (External Trigger Input in One-shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	200		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	100		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	100		ns

Table 5.39 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN input HIGH pulse width	100		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	100		ns

Table 5.40 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(UP)}$	TAiOUT input cycle time	2000		ns
$t_{w(UPH)}$	TAiOUT input HIGH pulse width	1000		ns
$t_{w(UPL)}$	TAiOUT input LOW pulse width	1000		ns
$t_{su(UP-TIN)}$	TAiOUT input setup time	400		ns
$t_{h(TIN-UP)}$	TAiOUT input hold time	400		ns

Table 5.41 Timer A Input (Two-phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle rime	800		ns
$t_{su(TAIN-TAOUT)}$	TAiOUT input setup time	200		ns
$t_{su(TAOUT-TAIN)}$	TAiIN input setup time	200		ns

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.42 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (counted on one edge)	100		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on one edge)	40		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on one edge)	40		ns
$t_{c(TB)}$	TBiIN input cycle time (counted on both edges)	200		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on both edges)	80		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on both edges)	80		ns

Table 5.43 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.44 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.45 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{C(AD)}$	$\overline{\text{ADTRG}}$ input cycle time (trigger able minimum)	1000		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ input LOW pulse width	125		ns

Table 5.46 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	100		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	100		ns
$t_{d(C-Q)}$	TXDi output delay time		80	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	70		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

Table 5.47 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ input HIGH pulse width	250		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ input LOW pulse width	250		ns

Switching Characteristics VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.50 Memory Expansion Mode and Microprocessor Mode (for 2- to 3-wait setting, external area access and multiplexed bus selection)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.12		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		(NOTE 1)		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{h(RD-CS)}$	Chip select output hold time (in relation to RD)		(NOTE 1)		ns
$t_{h(WR-CS)}$	Chip select output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time (in relation to BCLK)			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time (in relation to BCLK)		–4		ns
$t_{d(AD-ALE)}$	ALE signal output delay time (in relation to Address)		(NOTE 3)		ns
$t_{h(ALE-AD)}$	ALE signal output hold time (in relation to Address)		(NOTE 4)		ns
$t_{d(AD-RD)}$	RD signal output delay from the end of Address		0		ns
$t_{d(AD-WR)}$	WR signal output delay from the end of Address		0		ns
$t_{dZ(RD-AD)}$	Address output floating start time			8	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$

n is “2” for 2-wait setting, “3” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 25 \text{ [ns]}$$

4. Calculated according to the BCLK frequency as follows:

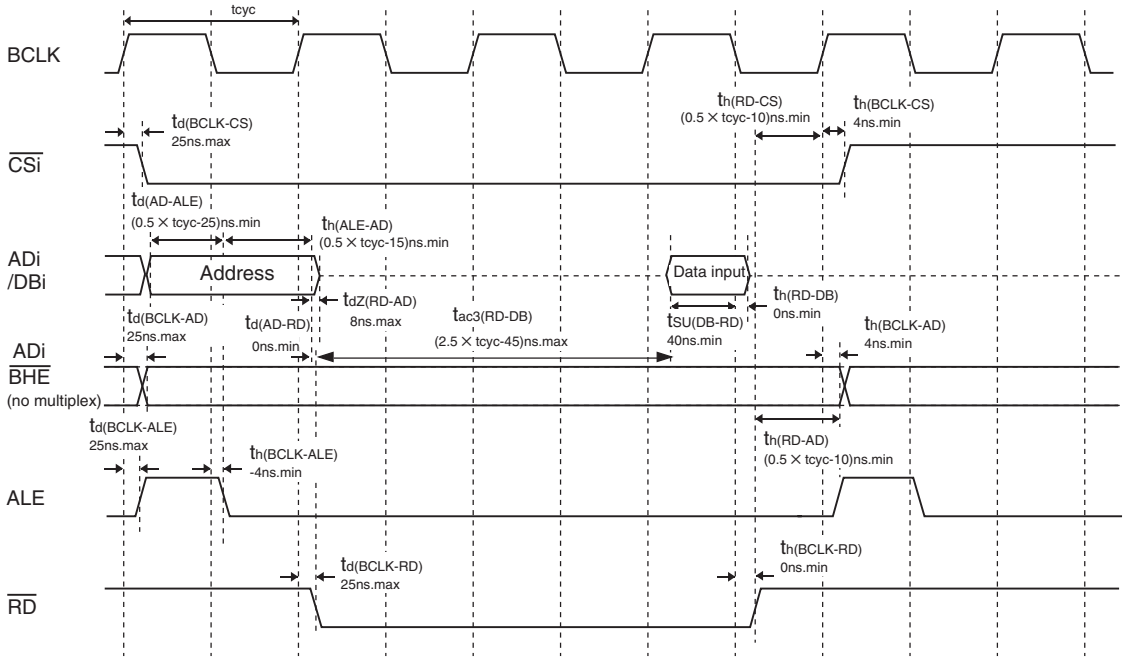
$$\frac{0.5 \times 10^9}{f(BCLK)} - 15 \text{ [ns]}$$

Memory Expansion Mode and Microprocessor Mode

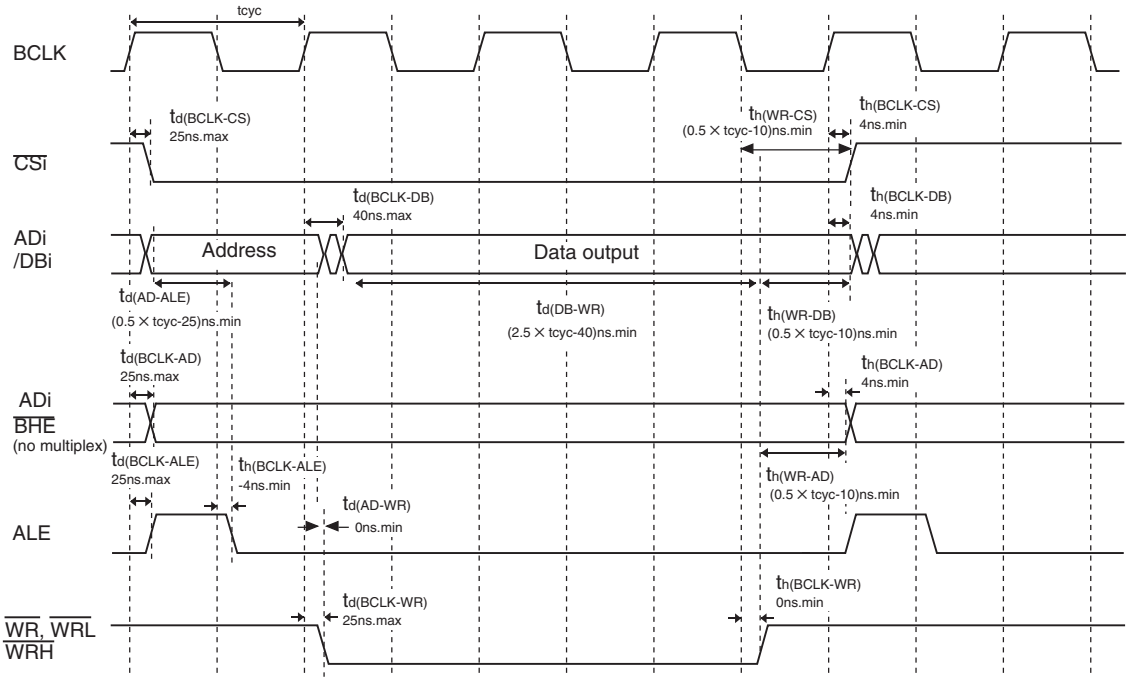
VCC = 5 V

(For 3-wait setting, external area access and multiplexed bus selection)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage : V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Output timing voltage : V_{OL} = 0.4 V, V_{OH} = 2.4 V

Figure 5.20 Timing Diagram (8)

Timing Requirements **VCC = 3.3 V**

(Referenced to VCC = 3.3 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.52 External Clock Input (XIN Input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External clock input cycle time	62.5		ns
$t_{w(H)}$	External clock input HIGH pulse width	25		ns
$t_{w(L)}$	External clock input LOW pulse width	25		ns
t_r	External clock rise time		15	ns
t_f	External clock fall time		15	ns

Table 5.53 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data input access time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data input access time (for setting with wait)		(NOTE 2)	ns
$t_{ac3(RD-DB)}$	Data input access time (when accessing multiplexed bus area)		(NOTE 3)	ns
$t_{su(DB-RD)}$	Data input setup time	50		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ input setup time	40		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ input setup time	50		ns
$t_{h(RD-DB)}$	Data input hold time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ input hold time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ input hold time	0		ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 60 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 60 \text{ [ns]}$$ n is “2” for 1-wait setting, “3” for 2-wait setting and “4” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

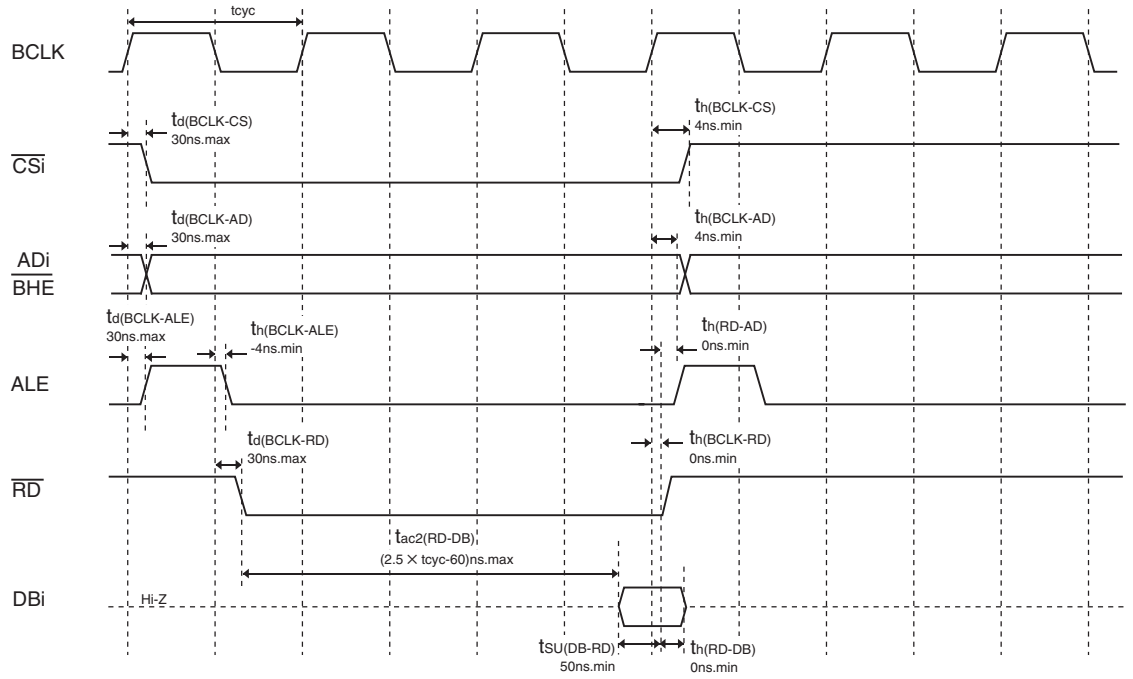
$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 60 \text{ [ns]}$$ n is “2” for 2-wait setting, “3” for 3-wait setting.

Memory Expansion Mode and Microprocessor Mode

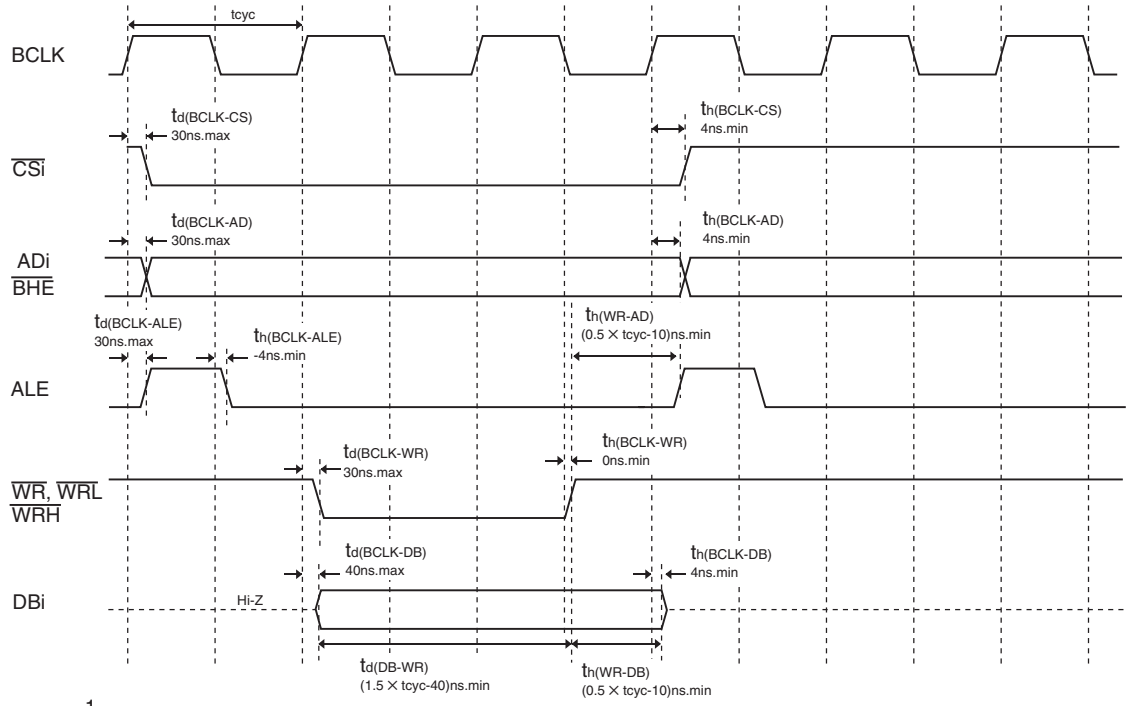
VCC = 3.3 V

(For 2-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.26 Timing Diagram (5)

REVISION HISTORY	M16C/6N Group (M16C/6N4) Data Sheet

Rev.	Date	Description	
		Page	Summary
2.40	Aug. 25, 2006	7, 8	Tables 1.3 and 1.4 List of Pin Names (1)(2) are added.
		9	Table 1.5 Pin Functions (1) • 3.0 to 5.5 V (Normal-ver.) is added to Description of Power supply input.
		22	Table 4.8 SFR Information (8) • The value of After Reset in IDB0 register is revised. • The value of After Reset in IDB1 register is revised.
		33	Table 5.3 Recommended Operating Conditions (2) • Power supply ripple is deleted. (three items) Figure 5.1 Voltage Fluctuation Timing is deleted.
		34	Table 5.4 Electrical Characteristics (1): Hysteresis XIN is deleted.
		52 to 87	5.2 Electrical Characteristics (Normal-ver.) is added.